

# 2PC4617

NPN general-purpose transistor

Rev. 05 — 17 November 2009

Product data sheet

## 1. Product profile

### 1.1 General description

NPN transistor in a SOT416 (SC-75) plastic package. The PNP complement is 2PA1774.

### 1.2 Features

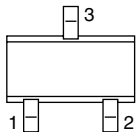
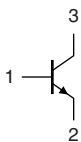
- Low current (max. 150 mA)
- Low voltage (max. 50 V)

### 1.3 Applications

- General-purpose switching and amplification in communication, Electronic Data Processing (EDP) and consumer applications.

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	base		 <i>sym021</i>
2	emitter		
3	collector		

## 3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
2PC4617Q	SC-75	plastic surface mounted package; 3 leads	SOT416
2PC4617R			
2PC4617S			

## 4. Marking

**Table 3. Marking codes**

Type number	Marking code
2PC4617Q	ZQ
2PC4617R	ZR
2PC4617S	ZS

## 5. Limiting values

**Table 4. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	60	V
$V_{CEO}$	collector-emitter voltage	open base	-	50	V
$V_{EBO}$	emitter-base voltage	open collector	-	7	V
$I_C$	collector current (DC)		-	150	mA
$I_{CM}$	peak collector current		-	200	mA
$I_{BM}$	peak base current		-	200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]	150	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C

[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1]	-	833	K/W

[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

## 7. Characteristics

**Table 6. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current	$I_E = 0\text{ A}$ ; $V_{CB} = 30\text{ V}$	-	-	100	nA
		$I_E = 0\text{ A}$ ; $V_{CB} = 30\text{ V}$ ; $T_j = 150\text{ }^{\circ}\text{C}$	-	-	5	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$I_C = 0\text{ A}$ ; $V_{EB} = 4\text{ V}$	-	-	100	nA
$h_{FE}$	DC current gain	$I_C = 1\text{ mA}$ ; $V_{CE} = 6\text{ V}$	[1]			
		2PC4617Q	120	-	270	
		2PC4617R	180	-	390	
		2PC4617S	270	-	560	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 50\text{ mA}$ ; $I_B = 5\text{ mA}$	[1]	-	200	mV
$C_c$	collector capacitance	$I_E = i_e = 0\text{ A}$ ; $V_{CB} = 12\text{ V}$ ; $f = 1\text{ MHz}$	-	-	1.5	pF
$f_T$	transition frequency	$I_C = 2\text{ mA}$ ; $V_{CE} = 12\text{ V}$ ; $f = 100\text{ MHz}$	[1]	100	-	MHz

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .

8. Package outline

Plastic surface-mounted package; 3 leads

SOT416

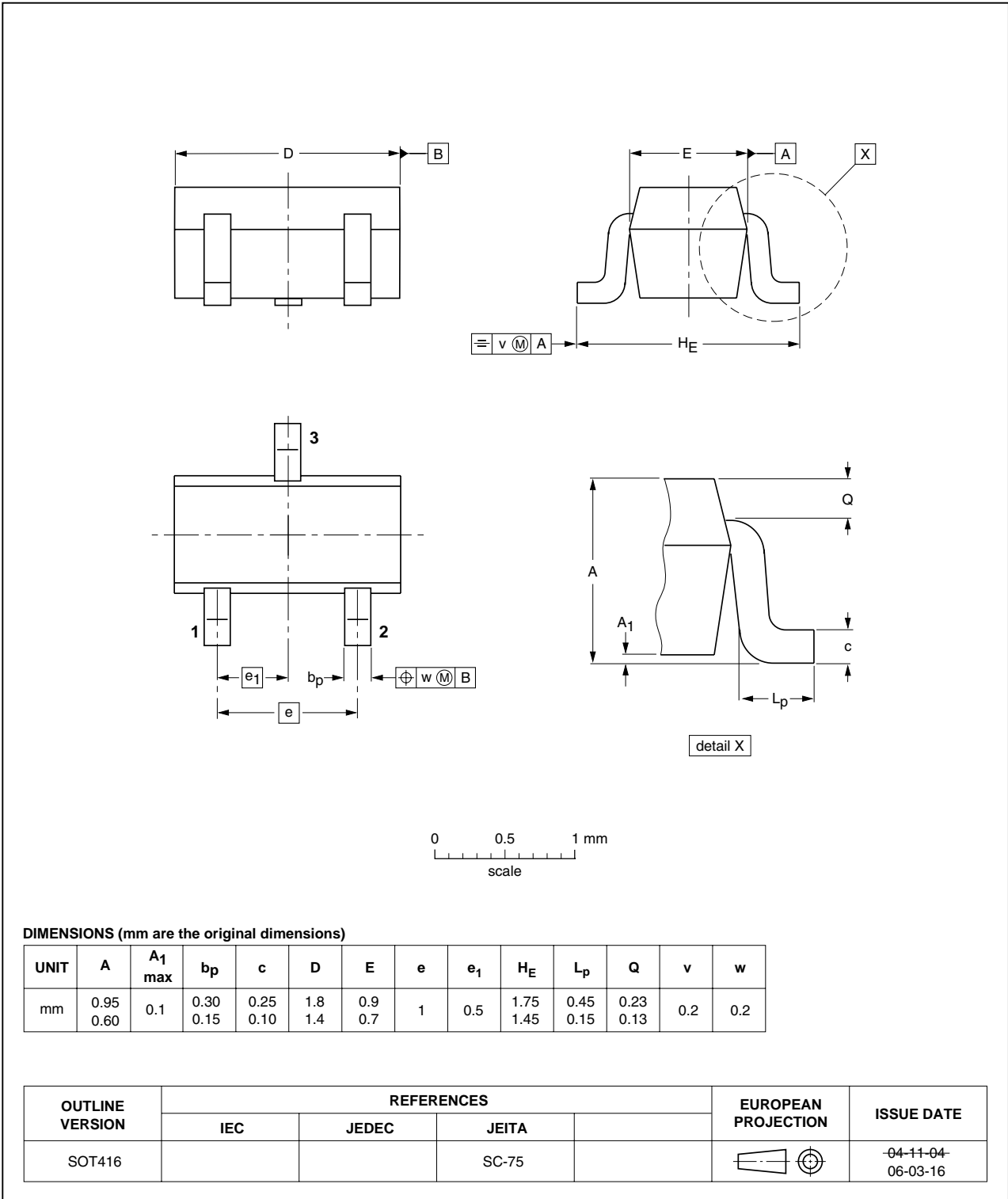


Fig 1. Package outline SOT416 (SC-75)

## 9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
2PC4617_5	20091117	Product data sheet	-	2PC4617_4
Modifications:		<ul style="list-style-type: none"><li>This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li><li><a href="#">Figure 1 "Package outline SOT416 (SC-75)"; updated</a></li></ul>		
2PC4617_4	20041125	Product data sheet	-	2PC4617_3
2PC4617_3	19990521	Product specification	-	2PC4617_2
2PC4617_2	19980721	Product specification	-	2PC4617_1
2PC4617_1	19970709	Product specification	-	-

## 10. Legal information

### 10.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

### 10.2 Definitions

**Draft** — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

**Short data sheet** — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

### 10.3 Disclaimers

**General** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental

damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

**Limiting values** — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Terms and conditions of sale** — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

**No offer to sell or license** — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

**Quick reference data** — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

### 10.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

## 11. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

## 12. Contents

<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description . . . . .	1
1.2	Features . . . . .	1
1.3	Applications . . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>1</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>1</b>
<b>4</b>	<b>Marking</b> . . . . .	<b>2</b>
<b>5</b>	<b>Limiting values</b> . . . . .	<b>2</b>
<b>6</b>	<b>Thermal characteristics</b> . . . . .	<b>2</b>
<b>7</b>	<b>Characteristics</b> . . . . .	<b>3</b>
<b>8</b>	<b>Package outline</b> . . . . .	<b>4</b>
<b>9</b>	<b>Revision history</b> . . . . .	<b>5</b>
<b>10</b>	<b>Legal information</b> . . . . .	<b>6</b>
10.1	Data sheet status . . . . .	6
10.2	Definitions . . . . .	6
10.3	Disclaimers . . . . .	6
10.4	Trademarks . . . . .	6
<b>11</b>	<b>Contact information</b> . . . . .	<b>6</b>
<b>12</b>	<b>Contents</b> . . . . .	<b>7</b>

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.



© NXP B.V. 2009.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

Date of release: 17 November 2009

Document identifier: 2PC4617\_5

## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9